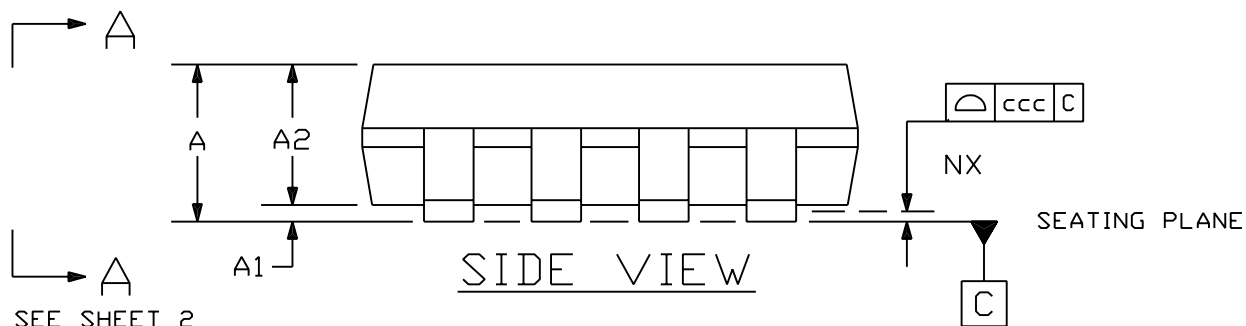


TOP VIEW



SIDE VIEW

FIGURE 1

JEDEC
SOLID STATE
PRODUCT OUTLINE

THIS *REGISTERED OUTLINE* HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.

TITLE
PLASTIC, LOW/THIN/VERY THIN
SHRINK SMALL OUTLINE PACKAGE
0.65 AND 0.50 PITCH

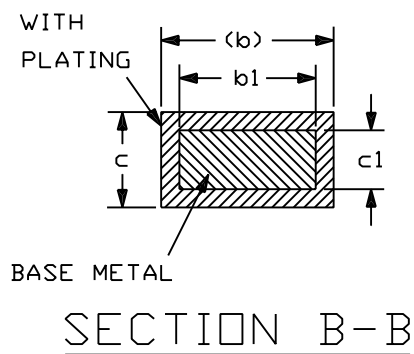
PACKAGE DESIGNATOR
(H)(L,T,V) SR-PDSO

ISSUE
E

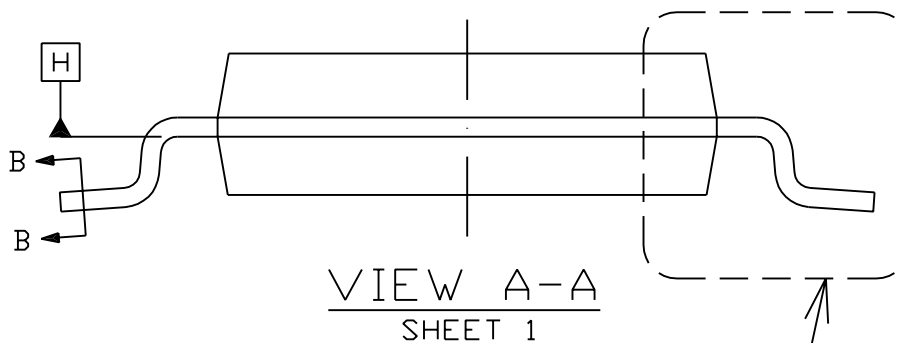
DATE
DEC
2004

MO-187

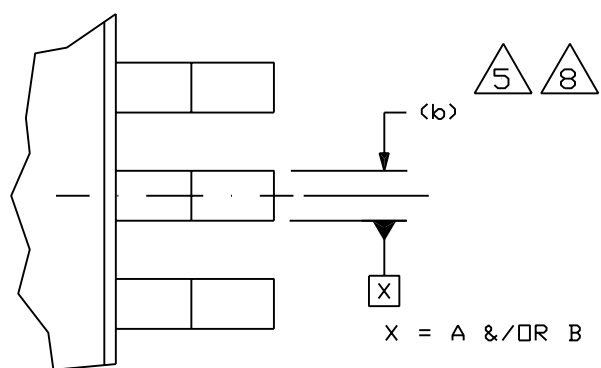
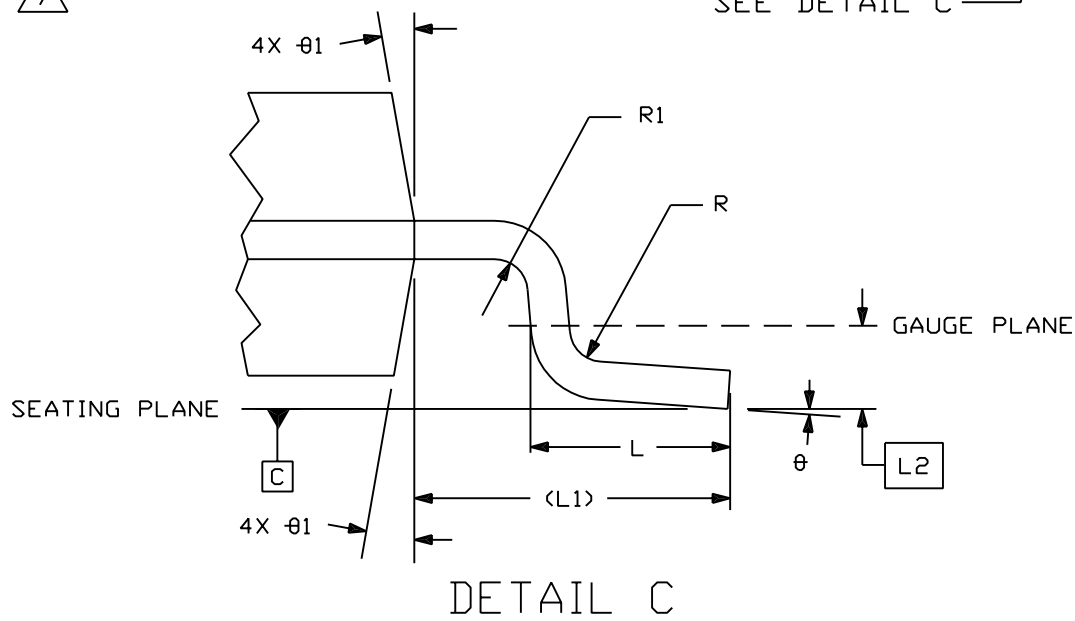
1
OF 8



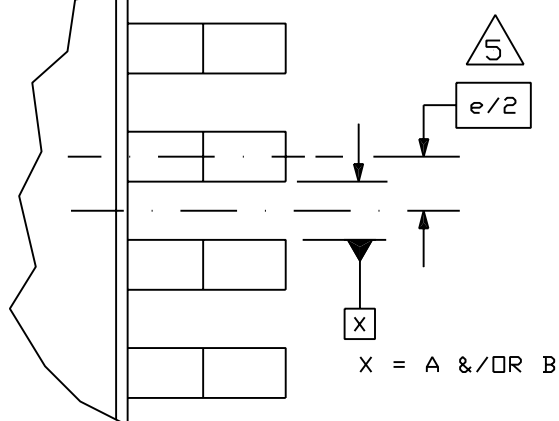
7



SEE DETAIL C



ODD LEAD SIDES
TOP VIEW



EVEN LEAD SIDES
TOP VIEW

FIGURE 2

JEDEC
SOLID STATE PRODUCT
OUTLINES

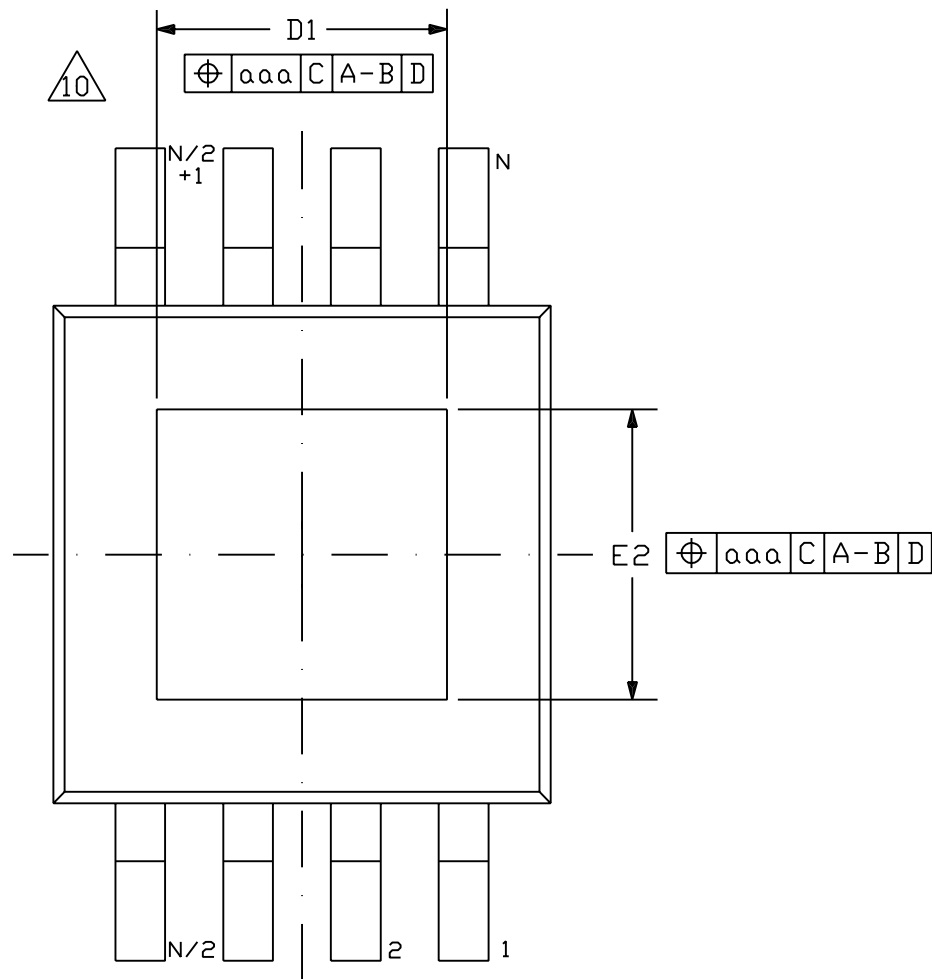
TITLE
PLASTIC, LOW/THIN/VERY THIN
SHRINK SMALL OUTLINE PACKAGE
0.65 AND 0.50 PITCH

ISSUE
E

DATE
DEC
2004

MO-187

2
OF 8



BOTTOM VIEW

<THERMALLY ENHANCED VARIATIONS ONLY>

COMMON DIMENSIONS AND TOLERANCES							
SYMBOL	ALL DIMENSIONS IN MILLIMETERS			NOTES	SYMBOL	TOLERANCES OF FORM AND POSITION	NOTES
	MIN	NOM	MAX				
A1	0	--	0.15		aaa	0.20	
c	0.08	--	0.23	7	bbb	0.25	
c1	0.08	--	0.18	7	ccc	0.10	
R	0.07	--	--				
R1	0.07	--	--		NOTES	1,2	
θ	0°	--	8°		REF.	11-552	
θ1	5°	--	15°		ISSUE	B	
NOTES	1,2						
REF.	11-430						
ISSUE	A						

VARIATIONS - THIN PROFILE												
SYMBOL	AA			BA						NOTES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.			
A	--	--	1.10	--	--	1.10						
A2	0.75	0.85	0.95	0.75	0.85	0.95						
b	0.22	--	0.38	0.17	--	0.33				7		
b1	0.22	0.30	0.33	0.17	0.20	0.23				7		
D	3.00 BSC			3.00 BSC						3,4		
D1	--			--								
E	4.90 BSC			4.90 BSC								
E1	3.00 BSC			3.00 BSC						3,4		
E2	--			--								
e	0.65 BSC			0.50 BSC								
e1	1.95 BSC			2.00 BSC								
L	0.40	0.60	0.80	0.40	0.60	0.80						
L1	0.95 REF			0.95 REF								
L2	0.25 BSC			0.25 BSC								
N	8			10						6,9		
TOLERANCES OF FORM AND POSITION												
ddd	0.13			0.08								
NOTE	1,8			1,8								
REF	11-430/11-552			11-552/11-694								
ISSUE	A/B			B/E								
SYMBOL	AA-T			BA-T						NOTES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.			
A	--	--	1.10	--	--	1.10						
A2	0.75	0.85	0.95	0.75	0.85	0.95						
b	0.22	--	0.38	0.17	--	0.33				7		
b1	0.22	0.30	0.33	0.17	0.20	0.23				7		
D	3.00 BSC			3.00 BSC						3,4		
D1	0.75	--	2.50	0.75	--	2.50				10		
E	4.90 BSC			4.90 BSC								
E1	3.00 BSC			3.00 BSC						3,4		
E2	0.75	--	2.50	0.75	--	2.50				10		
e	0.65 BSC			0.50 BSC								
e1	1.95 BSC			2.00 BSC								
L	0.40	0.60	0.80	0.40	0.60	0.80						
L1	0.95 REF			0.95 REF								
L2	0.25 BSC			0.25 BSC								
N	8			10						6,9		
TOLERANCES OF FORM AND POSITION												
ddd	0.13			0.08								
NOTE	1,8,10			1,8,10								
REF	11-409			11-409/11-694								
ISSUE	D			D/E								
JEDEC SOLID STATE PRODUCT OUTLINES				TITLE PLASTIC, LOW/THIN/VERY THIN SHRINK SMALL OUTLINE PACKAGE 0.65 AND 0.50 PITCH				ISSUE E	DATE DEC 2004	MD-187		5 OF 8

VARIATIONS - VERY THIN PROFILE

SYMBOL	CA									NOTES
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
A	--	--	1.00							
A2	0.60	0.70	0.85							
b	0.17	--	0.33							7
b1	0.17	0.20	0.23							7
D	2.00 BSC									3,4
D1	--									
E	3.10 BSC									
E1	2.30 BSC									3,4
E2	--									
e	0.50 BSC									
e1	1.50 BSC									
L	0.15	0.28	0.40							
L1	0.40 REF									
L2	0.12 BSC									
N	8									6,9
TOLERANCES OF FORM AND POSITION										
ddd	0.08									
NOTE	1,8									
REF	11-407/11-694									
ISSUE	C/E									

JEDEC SOLID STATE PRODUCT OUTLINES				TITLE PLASTIC, LOW/THIN/VERY THIN SHRINK SMALL OUTLINE PACKAGE 0.65 AND 0.50 PITCH		ISSUE E	DATE DEC 2004	MD-187	6 OF 8
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VARIATIONS - LOW PROFILE

SYMBOL	DA									NOTES
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
A	--	--	1.35							
A2	1.00	1.10	1.20							
b	0.15	--	0.30							7
b1	0.15	0.20	0.23							7
D	2.95 BSC									3,4
D1	--									
E	4.00 BSC									
E1	2.80 BSC									3,4
E2	--									
e	0.65 BSC									
e1	1.95 BSC									
L	0.20	0.40	0.60							
L1	0.60 REF									
L2	0.25 BSC									
N	8									6,9
	TOLERANCES OF FORM AND POSITION									
ddd	0.13									
NOTE	1,8									
REF	10-407									
ISSUE	C									

NOTES

1 DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

2 ALL DIMENSIONS ARE IN MILLIMETERS.

3 DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER END. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.15 mm PER SIDE. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM H.

4 THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM H.

5 DATUMS A-B TO BE DETERMINED AT DATUM H.

6 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

7 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 mm AND 0.15 mm FROM THE LEAD TIP.

8 DIMENSION 'b' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 mm TOTAL IN EXCESS OF THE 'b' DIMENSION AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN 0.07 mm.

9 DETAILS OF THE PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.

10 CAUTION SHOULD BE TAKEN DURING DESIGN, ASSEMBLY AND PROCESSING TO PREVENT DEPOSITED BOARD SOLDER FROM HOLDING THE LEADS OFF THE BOARD. THIS IS APPLICABLE TO THERMAL ENHANCED VARIATIONS WHERE 'A1' DIMENSION IS ALLOWED TO BE ZERO.

JEDEC SOLID STATE PRODUCT OUTLINES	TITLE PLASTIC, LOW/THIN/VERY THIN SHRINK SMALL OUTLINE PACKAGE 0.65 AND 0.50 PITCH	ISSUE E	DATE DEC 2004	MO-187	8 OF 8
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